



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE9250XLE			<b>Issued</b>	22. January 2018			
<b>MA#</b>	MA001675892							
<b>Package</b>	PG-TSON-8-1			<b>Weight*</b>	26.86 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.790	2.94	2.94	29396	29396
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		439	
	non noble metal	iron	7439-89-6	0.236	0.88		8788	
wire	non noble metal	copper	7440-50-8	9.586	35.68	36.61	356828	366165
	non noble metal	copper	7440-50-8	0.046	0.17	0.17	1730	1730
	encapsulation	organic material	carbon black	1333-86-4	0.031	0.11		1142
	plastics	epoxy resin	-	1.580	5.88		58819	
		inorganic material	silicondioxide	60676-86-0	13.730	51.12	57.11	511099
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14227	14227
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1618	1618
glue	plastics	epoxy resin	-	0.106	0.40		3951	
		noble metal	silver	7440-22-4	0.318	1.19	1.59	11853
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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